

2021.09.21 New Products Release

**Sales Release of “Solder Ball Mounting System applicable for $\Phi 30\mu\text{m}$ Ball”
for Circuit Miniaturization of Semiconductor Package**

We, AIMECHATEC, Ltd. (Head Office: Koyodai, Ryugasaki-shi, Ibaraki-pref. President: Isao Abe) are pleased to announce that “Solder Ball Mounting System applicable for $\Phi 30\mu\text{m}$ Ball” will be released as our new proposal for Semiconductor Business.

This system has been developed for Circuit Miniaturization of Semiconductor Package by applying Inkjet Technology as one of our core technologies. The system enabled application for Ultra fine pitch not by the conventional Flux Printing Method with stencil mask, but by Inkjet Technology which realized uniform Flux Coating. We have developed $\Phi 30\mu\text{m}$ Solder Ball Mounting System by this Flux-IJP (Ink-Jet Printer) Equipment together with the latest High-Accuracy Ball Mounter and High-Speed Inspection & Repair Equipment as Total Solution (Patented).

Our Inkjet Technology has been delivered to many customers mainly in Flat Panel Display Market. With our Inkjet Technology cultivated for many years, we will challenge and achieve new system for further Circuit Miniaturization of Semiconductor Package Process.

Demands for Semiconductor Packages such as Data Center, Mobile Devices and In-vehicle applications have been expanding in the background of 5G Communication, Big Data, IoT and AI. At the same time, Circuit Miniaturization and Solder Ball Diameter Reduction are required in accordance with Market Needs for High-Speed, High-Functionality, and Smaller/ Compact-Sizing. In particular, the needs are extremely higher in the advanced Semiconductor Package and then this Solder Ball Mounter System is earnestly considered to be applied.

We will continue to contribute to society by improving more convenient and affluent lifestyles through our technological innovations for manufacturing processes.

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https://www.ai-mech.com/wp_en/newproducts/



30um Solder Ball Mounting System